

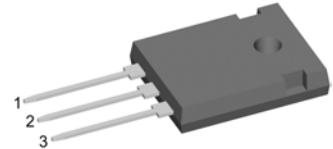
High Efficiency Thyristor

V_{RRM} = 1200 V
 I_{TAV} = 20 A
 V_T = 1,3 V

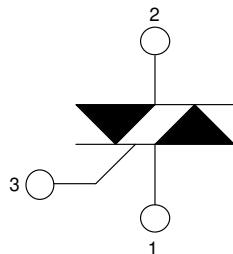
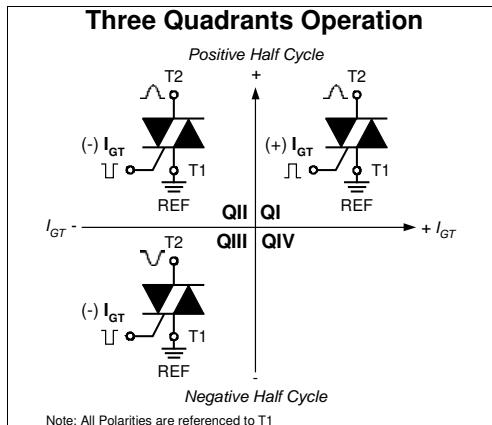
Three Quadrants operation: QI - QIII
1~ Triac

Part number

CLA40MT1200NHR



Backside: isolated



Features / Advantages:

- Triac for line frequency
- Three Quadrants Operation - QI - QIII
- Planar passivated chip
- Long-term stability of blocking currents and voltages

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: ISO247

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Disclaimer Notice

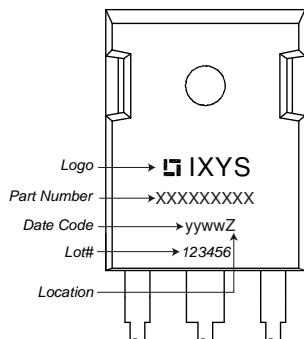
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Thyristor

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ\text{C}$			1300	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ\text{C}$			1200	V
$I_{R/D}$	reverse current, drain current	$V_{R/D} = 1200 \text{ V}$ $V_{R/D} = 1200 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		50 1	μA mA
V_T	forward voltage drop	$I_T = 20 \text{ A}$ $I_T = 40 \text{ A}$ $I_T = 20 \text{ A}$ $I_T = 40 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		1,31 1,63 1,30 1,71	V V V V
I_{TAV}	average forward current	$T_C = 100^\circ\text{C}$	$T_{VJ} = 150^\circ\text{C}$		20	A
I_{RMS}	RMS forward current per phase	180° sine			31	A
V_{TO}	threshold voltage	r_T slope resistance } for power loss calculation only	$T_{VJ} = 150^\circ\text{C}$		0,86	V
	slope resistance				21,4	$\text{m}\Omega$
R_{thJC}	thermal resistance junction to case				1,2	K/W
R_{thCH}	thermal resistance case to heatsink			0,25		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ\text{C}$		105	W
I_{TSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0 \text{ V}$ $T_{VJ} = 150^\circ\text{C}$ $V_R = 0 \text{ V}$		180 195 155 165	A
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0 \text{ V}$ $T_{VJ} = 150^\circ\text{C}$ $V_R = 0 \text{ V}$		160 160 120 115	A^2s A^2s A^2s A^2s
C_J	junction capacitance	$V_R = 230 \text{ V}$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ\text{C}$		9	pF
P_{GM}	max. gate power dissipation	$t_p = 30 \mu\text{s}$ $t_p = 300 \mu\text{s}$	$T_C = 150^\circ\text{C}$		5 2,5 0,5	W W W
P_{GAV}	average gate power dissipation					
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 150^\circ\text{C}; f = 50 \text{ Hz}$ repetitive, $I_T = 60 \text{ A}$ $t_p = 200 \mu\text{s}; di_G/dt = 0,15 \text{ A}/\mu\text{s};$ $I_G = 0,15 \text{ A}; V_D = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 20 \text{ A}$			150	$\text{A}/\mu\text{s}$
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$; method 1 (linear voltage rise)	$T_{VJ} = 150^\circ\text{C}$		500	$\text{V}/\mu\text{s}$
V_{GT}	gate trigger voltage	$V_D = 6 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$		1,5 2,5	V V
I_{GT}	gate trigger current	$V_D = 6 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$		± 60 ± 100	mA mA
V_{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150^\circ\text{C}$		0,2	V
I_{GD}	gate non-trigger current				± 3	mA
I_L	latching current	$t_p = 10 \mu\text{s}$ $I_G = 0,1 \text{ A}; di_G/dt = 0,1 \text{ A}/\mu\text{s}$	$T_{VJ} = 25^\circ\text{C}$		75	mA
I_H	holding current	$V_D = 6 \text{ V}$ $R_{GK} = \infty$	$T_{VJ} = 25^\circ\text{C}$		50	mA
t_{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$ $I_G = 0,1 \text{ A}; di_G/dt = 0,1 \text{ A}/\mu\text{s}$	$T_{VJ} = 25^\circ\text{C}$		2	μs
t_q	turn-off time	$V_R = 100 \text{ V}; I_T = 20 \text{ A}; V_D = \frac{2}{3} V_{DRM}$ $T_{VJ} = 125^\circ\text{C}$ $di/dt = 10 \text{ A}/\mu\text{s}; dv/dt = 20 \text{ V}/\mu\text{s}; t_p = 200 \mu\text{s}$		150		μs

Package ISO247			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			50	A
T_{VJ}	virtual junction temperature		-55		150	°C
T_{op}	operation temperature		-55		125	°C
T_{stg}	storage temperature		-55		150	°C
Weight				6		g
M_D	mounting torque		0,8		1,2	Nm
F_c	mounting force with clip		20		120	N
$d_{Spp/App}$	creepage distance on surface striking distance through air		terminal to terminal	2,7		mm
$d_{Spb/Apb}$			terminal to backside	4,1		mm
V_{ISOL}	isolation voltage	$t = 1$ second $t = 1$ minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA		3600 3000	V V

Product Marking



Part description

C = Thyristor (SCR)
 L = High Efficiency Thyristor
 A = (up to 1200V)
 40 = Current Rating [A]
 MT = 1~ Triac
 1200 = Reverse Voltage [V]
 N = Three Quadrants operation: Q1 - QIII
 HR = ISO247 (3)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CLA40MT1200NHR	CLA40MT1200NHR	Tube	30	521685

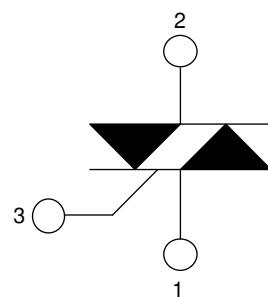
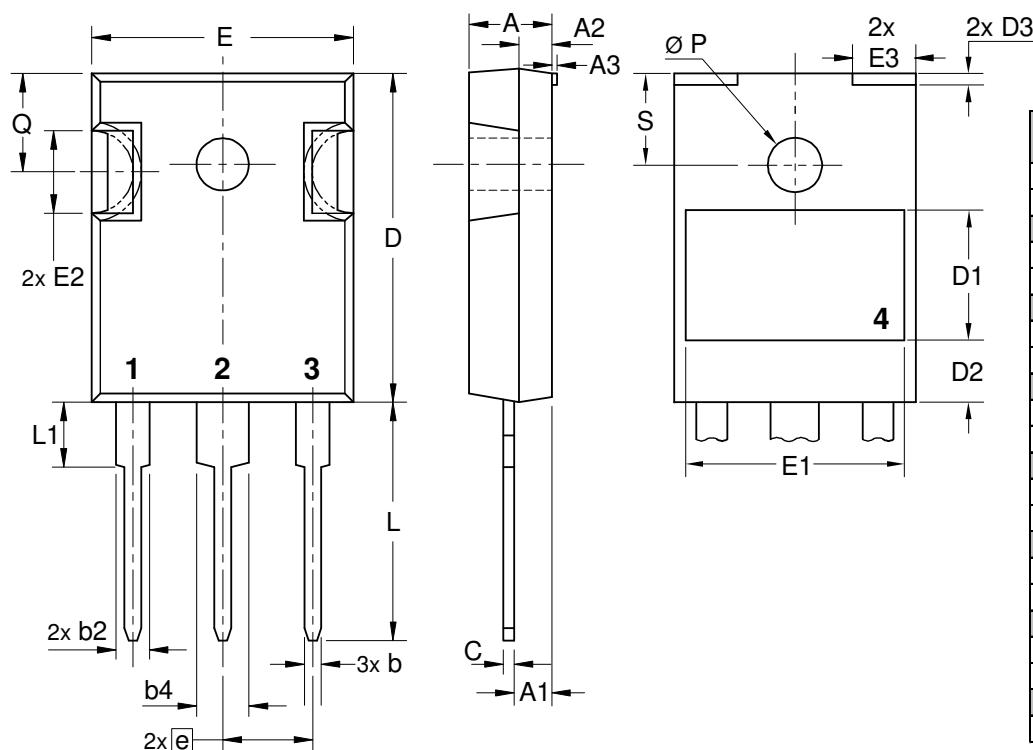
Similar Part	Package	Voltage class
CLA60MT1200NHR	ISO247 (3)	1200
CLA80MT1200NHR	ISO247 (3)	1200

Equivalent Circuits for Simulation

* on die level

$T_{VJ} = 150^\circ\text{C}$

Thyristor	
V_0	threshold voltage
$V_{0\max}$	0,86 V
$R_{0\max}$	slope resistance * 18,9 mΩ

Outlines ISO247


Thyristor

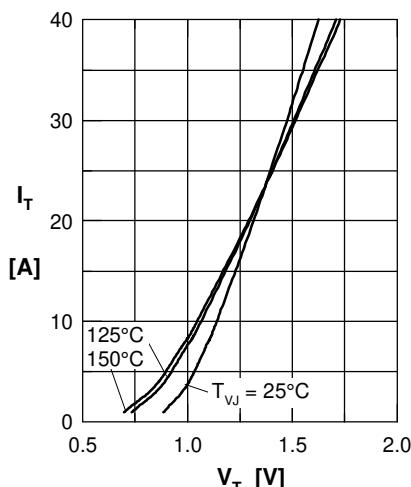


Fig. 1 Forward characteristics

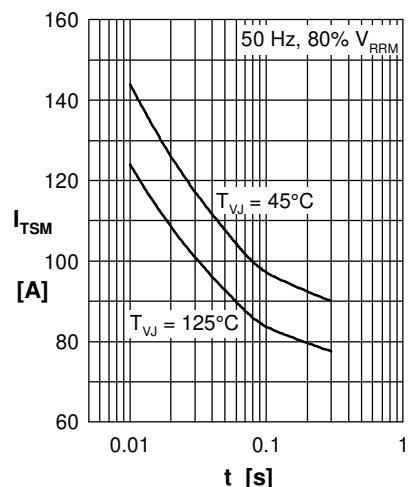


Fig. 2 Surge overload current

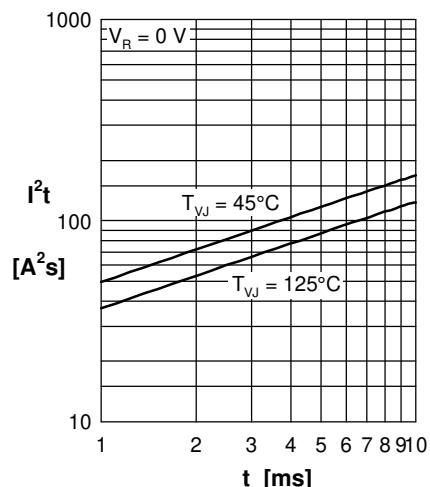


Fig. 3 I^2t versus time (1-10 ms)

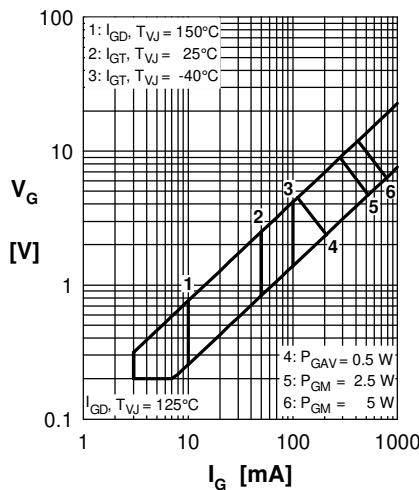


Fig. 4 Gate trigger characteristics

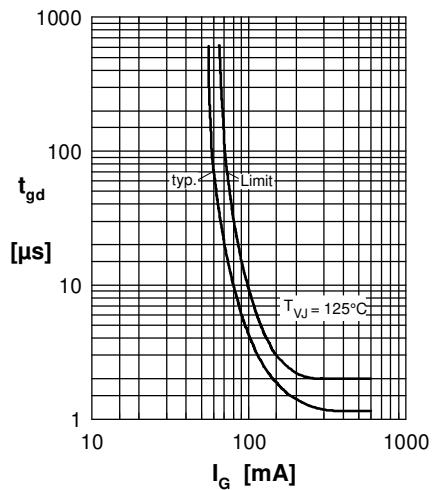


Fig. 5 Gate controlled delay time

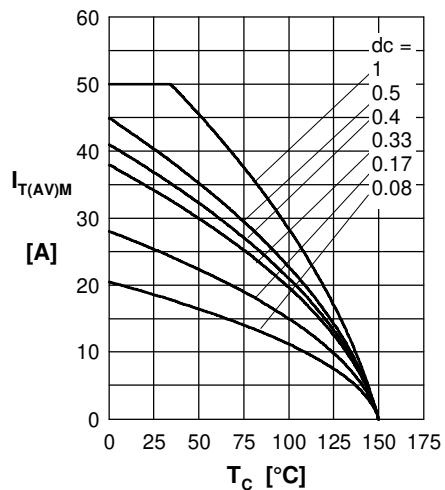


Fig. 6 Max. forward current at case temperature

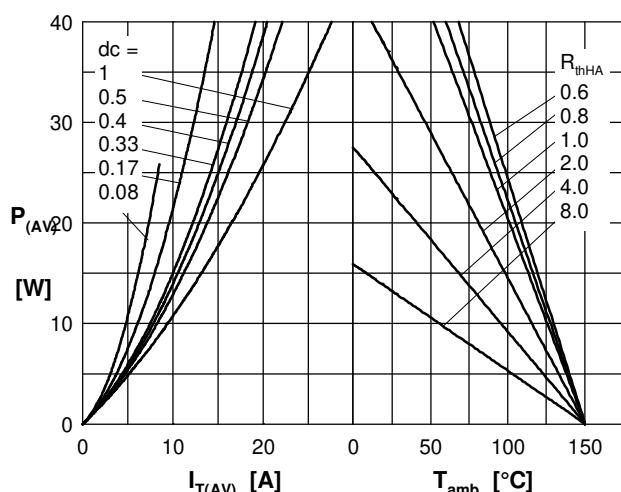


Fig. 7a Power dissipation versus direct output current
Fig. 7b and ambient temperature

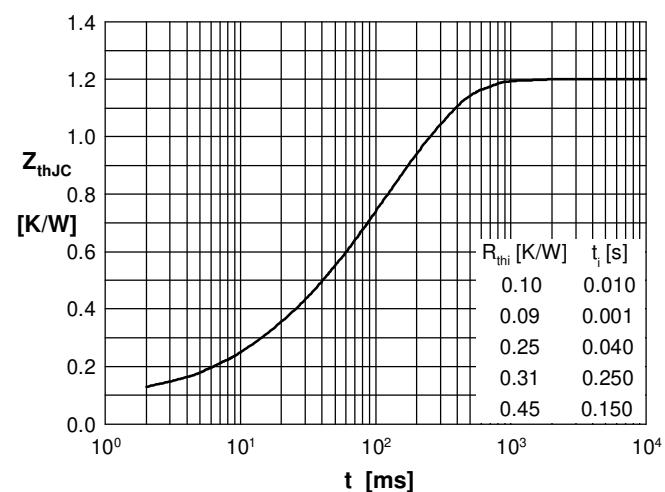


Fig. 7b Transient thermal impedance junction to case